

**CLAIMS:**

What is claimed is:

1. A heat-dissipating device for an heat generating electronic component,  
comprising:  
a heat-conducting plate having a holding surface;  
a heat sink defining a clipping hole formed at a bottom thereof; and  
5 a heat-conducting block received in the clipping hole and disposed on the holding  
surface.
2. The heat-dissipating device as claimed in claim 1, wherein the heat sink has a  
plurality of fins vertically disposed and arranged parallel to each other for air flowing.
3. The heat-dissipating device as claimed in claim 1, wherein the clipping hole of  
the heat sink is defined from a front side of the heat sink to a rear side of the heat sink.
4. The heat-dissipating device as claimed in claim 1, wherein the holding surface  
of the heat-conducting plate is non-planar.
5. The heat-dissipating device as claimed in claim 1, wherein the heat-  
conducting block is a heat pipe.
6. The heat-dissipating device as claimed in claim 1, wherein the heat-  
conducting block is cylindrical.

7. The heat-dissipating device as claimed in claim 1, further comprising:  
a fixed base disposed around a heat generating electronic component on a printed circuit board and receiving the heat sink;

5 a frame disposed around the heat sink and having two shoulder portion respectively  
formed at two opposite top sides thereof and two elastic elements respectively disposed on  
the two shoulder portions;

a fan fixed on the frame; and

10 two clips respectively clipping the fixed base and pressing the two elastic elements of  
the frame, so that the heat-conducting plate abuts against the heat generating electronic  
component.

8. The heat-dissipating device as claimed in claim 1, wherein the holding surface  
of the heat-conducting plate is a concave shape.